

## **XCS Series Data Sheet**

PN: 602345002, Model: C6-S7-3070-XCS-28-48-146-SX-1G-405-3R



The new 3D sensors of the XCS series are particularly suitable for high-performance applications in the electronics industry thanks to their enormous precision and extreme speed. The sensors are characterized by an optimized laser with homogeneous thickness along the laser line, which guarantees precise detection of even the smallest structures. This enables high-precision inspection applications with high repeatability, which is ideal for the inspection of ball grid arrays (BGAs), among other things. The innovative clean beam function protects the laser from external interference and ensures a uniform intensity distribution, which further increases reliability. The sensor's dual-head option eliminates occlusions and achieves profile speeds of up to 140 kHz with the 3070-WARP version, speeding up data analysis and increasing efficiency.

- Unique 3D scan results without occlusion due to dual-head option and extremely high resolution
- High precision and repeatability thanks to high-quality laser line projection
- Two different sensor resolutions available (3070, 4090)
- Unrivaled optical resolution for electronic inspection (e.g. BGA inspection) with a field of view of up to 53 mm
- Highest inspection speed available with 3070 WARP sensor









## **Model Information**

Model Name	C6-S7-3070-XCS-28-48-146-SX-1G-405-3R	
Part Number	602345002	
Sensor configuration	Single	

## **Detector/Performance specifications**

Detector	CMOS   Global Shutter
Resolution	3072 x 1020 pixels
Physical size	20.275 x 6.732 mm
Pixel size	6.6 x 6.6 µm
Points per profile	3072
Profile speed at 200 rows	4798.0 Hz
Maximum profile speed	66489.0 Hz
Linearity Z-Axis	0.051 % of calibrated Z-Range

## X Field of View

	Nominal	Near Field	Far Field	
Scan Width	47.9 mm	44.5 mm	51.3 mm	
X-Resolution	15.6 μm	14.5 μm	16.7 μm	
Z-Resolution	0.5 µm	-	-	

## **Z** Field of View

	Full	Near Field	Far Field
Z-Range	20.0 mm	10.0 mm	10.0 mm

# **Laser/Geometry specifications**

Working Distance	146.0 mm
Triangulation Angle	28.0 °
Laser Safety Class	3R
Laser Wavelength	405.0 nm
Laser Output Power	80.0 mW
Laser Line Width	21.0 µm

# **Interface specifications**

Ethernet	Gigabit-Ethernet   1.000 Mbit/s	
Encoder	A+, A-, B+, B-, Z+, Z-   RS-422   TTL	
Digital inputs	2x isolated digital inputs   5V - 24V DC	
Digital outputs	2x isolated digital outputs 15V - 24V DC	

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## **Electrical/Mechanical specifications**

Sensor power supply	12V - 24V DC   27V DC Max.	
Power consumption	- W	
Laser power supply	12V - 24V DC	
Connectors	Power&I/O: M12-Connector   17-pin Ethernet: M12-Connector   8-pin   A-coded	
Housing material	Anodized aluminum	
Dimensions (L x W x H)	159.0 x 60.0 x 113.0 mm	
Weight	1750.0 g	

### **Environmental conditions**

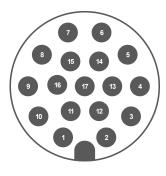
Temperatures Operating: 0 °C - +40 °C   Storage: -20 °C - +80 °C		
Humidity	20 % - 80 % (non-condensing)	
Vibration resistance Sinusoidal: DIN EN 60068-2-6:2008-10: 2 g   10 Hz - 150 Hz   Random: DIN EN 60068-2-64:2020-09: 7 g   10 Hz - 500 Hz		
Shock resistance	DIN EN 60068-2-27: 2010-02: 15 g   3 ms	
Protection class	IP67   According to IEC 60529	

## Software/Features

Supported standards GenICam   GigEVision		
Firmware features RegionTracking   RegionSearch   MultiRegion   MultiPart   AutoStart   HistoryBuffer   MultiSlope   MultiPeak		
Software	SolutionPackage   MetrologyPackage   cxSDK with wrappers for C, C++, Python and Matlab	

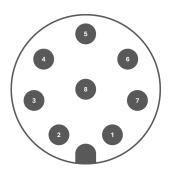
### **Connectors**

#### M12 17-Pin: A-Coded Male Connector



1	ENC_Z-
2	LASER_Supply
3	ENC_Z+
4	ENC_B+
5	GND
6	ENC_B-
7	ENC_A-
8	VCC_EXT
9	GND_EXT
10	ENC_A+
11	ENC_GND
12	OUT2
13	IN1
14	IN2
15	OUT_Supply
16	OUT1
17	IO_GND
Shield	SHIELD

#### M12 8-Pin: A-Coded Female Connector



1	BI_DC-
2	BI_DD+
3	BI_DD-
4	BI_DA-
5	BI_DB+
6	BI_DA+
7	BI_DC+
8	BI_DB-
Shield	SHIELD





